

between the composition and a material making up an ink discharge nozzle face of the ink-jet recording head is within the range of 30° to 170° .

39. The manufacturing process of claim 37, wherein the conductive material is contained in an amount of 0.01 wt% to 10 wt% of the composition, and wherein the composition has a viscosity of 1 to 20 cps.

40. The manufacturing process of claim 37, wherein the conductive material is contained in an amount of 0.01 wt% to 10 wt% of the composition, and wherein the composition has a surface tension of 20 to 70 dyne/cm.

41. The manufacturing process of claim 37, wherein the conductive material is contained in an amount of 0.01 wt% to 10 wt% of the composition, wherein the composition has a viscosity of 1 to 20 cps, and wherein a contact angle between the composition and a material making up an ink discharge nozzle face of the ink-jet recording head is within the range of 30° to 170° .

42. The manufacturing process of claim 37, wherein the conductive material is contained in an amount of 0.01 wt% to 10 wt% of the composition, and wherein the composition has a viscosity of 1 to 20 cps and a surface tension of 20 to 70 dyne/cm.

43. The manufacturing process of claim 37, wherein the conductive material is contained in an amount of 0.01 wt% to 10 wt% of the composition, wherein the composition has a surface tension of 20 to 70 dyne/cm, and wherein a contact angle between the composition and a material making up an ink discharge nozzle face of the ink-jet recording head is within the range of 30° to 170° .

44. The manufacturing process of claim 37, wherein the conductive material is contained in an amount of 0.01 wt% to 10 wt% of the composition, wherein the composition has a viscosity of 1 to 20 cps and a surface tension of 20 to 70 dyne/cm, and wherein a contact angle

between the composition and a material making up an ink discharge nozzle face of the ink-jet recording head is within the range of 30° to 170° .

45. The manufacturing process according to claim 37, wherein the conductive material is present in a dissolved or dispersed state in the solvent and the solvent is a polar solvent.

46. The manufacturing process according to claim 45, wherein the polar solvent is a mixed solvent of water and a lower alcohol.

47. The manufacturing process according to claim 46, wherein the lower alcohol is methanol or ethanol.

48. The manufacturing process according to claim 45, wherein the polar solvent is a mixed solvent of water and at least one solvent selected from the group consisting of mono and dialkyl ethers of ethylene glycol and their derivatives.

49. The manufacturing process according to claim 48, wherein the at least one solvent selected from the group is ethoxy ethanol.

50. The manufacturing process according to claim 37, further comprising a lubricant.

51. The manufacturing process according to claim 50, wherein the lubricant is glycerin.

52. An organic EL element manufactured by the manufacturing process according to claim 37.

53. The organic EL element of claim 52, wherein a film thickness of the hole injecting and transporting layer is $0.1\mu\text{m}$ or less.

54. The organic EL element of claim 52, wherein a film resistance of the hole injecting and transporting layer is in the range $0.5 \times 10^9 \Omega/\text{m}^2$ to $5 \times 10^9 \Omega/\text{m}^2$.

55. A process for manufacturing a composition used for a hole injecting and transporting layer of an organic EL element having a stacked structure including the hole injecting and transporting layer and a light-emitting layer, the composition comprising (1) a conductive material containing at least polyethylenedioxithiophene and polystyrene sulfonic acid, and (2) a solvent, the process comprising:

sonicating a mixture of the conductive material and the solvent; and

filtering the mixture of the conductive material and the solvent.

56. A manufacturing process for an organic EL element having a stacked structure including a hole injecting and transporting layer and a light-emitting layer formed within a partitioning member which is divided into individual pixel areas, the method comprising:

forming the partitioning member on a substrate, the partitioning member having openings corresponding to pixel areas;

filling the openings with a composition for the hole injecting and transporting layer using an ink-jet recording head, the composition comprising at least a material for a hole injecting and transporting layer and a polar solvent; and

drying the composition filled in the openings to form the hole injecting and transporting layer.

57. A composition used for forming a pattern formation of a hole injecting and transporting layer of an organic EL element using an ink-jet recording head, the composition comprising at least polyethylenedioxithiophene and polystyrene sulfonic acid.

58. A composition used for forming a pattern formation of a hole injecting and transporting layer of an organic EL element using an ink-jet recording head, the composition comprising at least a material for a hole injecting and transporting layer and a polar solvent as a solvent.